

**REMARKS/ARGUMENTS**

Further in response to the Final Office Action of April 24, 2008 and the Advisory Action of August 18, 2008, relating to the above-identified application, applicants file herewith a petition for a three-month extension of time, together with the associated fee.

The claims under examination are Claims 17-20.

Applicants reserve the right to file a divisional application with regard to the non-elected subject matter represented by Claims 1-16 and 21-32.

The rejection of Claims 17-19 under 35 U.S.C. § 103(a) as unpatentable in view of *Shimizu*, US 6,670,098, taken with *Dixon*, US 4,800,461, is again traversed and reconsideration is respectfully requested.

Independent Claim 17 is generic to dependent Claims 18 and 19 and defines a multilayer flexible wiring board formed of (i) a plurality of single sided wiring boards; (ii) a flexible wiring board and (iii) an adhesive layer. The plurality of single sided wiring boards and the flexible wiring board are laminated together with the adhesive layer. Reference is made to the present application, page 9, line 16 to page 10, line 9, *et. seq.* and Fig. 5(b) which describes the present invention as a multilayer flexible wiring board comprising a plurality of single sided wiring boards having a wiring pattern formed on one side of a substrate made of an insulating material and two-layer conductor posts and a flexible wiring board having on at least one side thereof pads for connection to the conductor posts and an adhesive layer there between having a flux function.

Substantially no surface coating is applied on the wiring pattern on a rigid portion of a flexible wiring board. However, a surface coating is applied on the flexible portion of the flexible wiring board which extends from the rigid portion. This feature of the invention is clearly defined in Claim 17, as amended herein.

The Final Office Action, on page 3, acknowledges that *Shimizu* does not disclose the wiring board as a flexible board.

The Final Official Action also admits that middle portion 51 of *Shimizu* is rigid. This is shown in *Shimizu* at col. 11 lines 1-10.

The Official Action alleges that boards with flexible middle portions with coatings on the flexible portion for protection are known and points to the patent of *Dixon*, US 4,800,461. This reference discloses a circuit board with a flexible portion having an insulating coating (20) on the flexible portion; see col. 3, lines 45-49. However, in *Dixon*, all the structural elements such as the overcoat and other layers are laminated in one lump.

The rejection is based on the proposition that since circuit boards with a flexible portion are shown in *Dixon*, a person skilled in the art would readily replace the middle portion of *Shimizu*'s board with a flexible member.

In the present invention, the surface coating is provided only in the flexible portion. As a result, conductor posts can be short to attain high connection reliability, and the resulting wiring board can be thin because the multilayer portion includes substantially no surface coating as

pointed out in Claim 17, as amended. This benefit could not have been predicted from either of the references.

Since *Shimizu* teaches that the middle layer must be rigid, it would be contrary to the teachings and explicit instructions of the reference to disregard this requirement for rigidity. Applicants respectfully submit that a person having ordinary skill in this technology would not go contrary to the teachings of *Shimizu* and replace the rigid member with a flexible member having the features recited in Claim 17.

Merely because flexible portions are used in some boards (*Dixon*) does not mean that a person skilled in the art would replace *Shimizu*'s rigid portion with a flexible portion in the absence of any reason to do so.

Applicants respectfully submit that no *prima facie* obviousness has been established by the combination of references relied on in the Final Office Action. No reasoned explanation has been provided to establish that a person skilled in the art would be lead to modify the *Shimizu* product. Therefore, the rejection should be withdrawn.

Since Claims 18 and 19 depend on Claim 17, the same reasons apply here. The record simply does not explain why a person skilled in the art would find a reasonable basis to modify *Shimizu* with the expectation of achieving a beneficial result.

App. No. 10/534,962  
Amend. w/RCE dated Feb. 23, 2009

---

The rejection of Claim 20 under 35 U.S.C. 103(a) in view of *Shimizu* taken with *Dixon* and further in view of *Nakamura*, US 6,395,993 is traversed and reconsideration is respectfully requested.

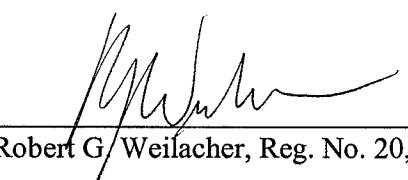
The combination of *Shimizu* and *Dixon* has already been discussed and all the comments apply here as well. *Nakamura* fails to teach or suggest that the rigid middle layer of *Shimizu* should be replaced with a flexible layer and that some advantage or benefit would be obtained. Without a teaching in the prior art that the product of *Shimizu* would be benefited in some way by such a modification, the entire construction of references collapses and clearly fails to establish *prima facie* obviousness of the subject matter of Claim 20.

Applicants respectfully request that the rejections be withdrawn and the claims be allowed.

Respectfully submitted,

SMITH, GAMBRELL & RUSSELL, LLP

By:

  
Robert G. Weilacher, Reg. No. 20,531

Dated: February 23, 2009  
Suite 3100, Promenade II  
1230 Peachtree Street, N.E.  
Atlanta, Georgia 30309-3592  
Telephone: (404) 815-3593  
Facsimile: (404) 685-6893